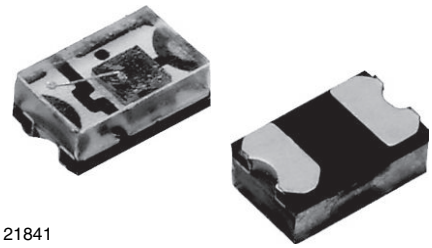
Silicon PIN Photodiode



21841

FEATURES

- Package type: surface mount
- Package form: 0805
- Dimensions (L x W x H in mm): 2 x 1.25 x 0.85
- Radiant sensitive area (in mm^2): 0.23
- High photo sensitivity
- High radiant sensitivity
- Suitable for visible and near infrared radiation
- Fast response times
- Angle of half sensitivity: φ = ± 60°
- Floor life: 168 h, MSL 3, acc. J-STD-020
- Lead (Pb)-free reflow soldering
- AEC-Q101 qualified
- Compliant to RoHS directive 2002/95/EC and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition

AUTOMOTIVE GRADE

Pb-free

e4

RoHS COMPLIANT

HALOGEN FREE

DESCRIPTION

TEMD7000X01 is a high speed and high sensitive PIN photodiode. It is a miniature surface mount device (SMD) including the chip with a 0.23 mm^2 sensitive area detecting visible and near infrared radiation.

APPLICATIONS

- High speed photo detector

PRODUCT SUMMARY			
COMPONENT	**I_{ra} (μA)**	**φ (deg)**	**$\lambda_{0.1}$ (nm)**
TEMD7000X01	3	± 60	430 to 1100

Note

- Test conditions see table “Basic Characteristics”

ORDERING INFORMATION			
ORDERING CODE	**PACKAGING**	**REMARKS**	**PACKAGE FORM**
TEMD7000X01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	0805

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T_{amb} = 25 °C, unless otherwise specified)				
PARAMETER	**TEST CONDITION**	**SYMBOL**	**VALUE**	**UNIT**
Reverse voltage		V_R	60	V
Power dissipation	$T_{amb} \leq 25$ °C	P_V	215	mW
Junction temperature		T_j	100	°C
Operating temperature range		T_{amb}	- 40 to + 100	°C
Storage temperature range		T_{stg}	- 40 to + 100	°C
Soldering temperature	Acc. reflow solder profile fig. 8	T_{sd}	260	°C
Thermal resistance junction/ambient	Acc. J-STD-051	R_{thJA}	270	K/W

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)						
PARAMETER	**TEST CONDITION**	**SYMBOL**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Forward voltage	I_F = 50 mA	V_F		1		V
Breakdown voltage	I_R = 100 µA, E = 0	$V_{(BR)}$	60			V
Reverse dark current	V_R = 10 V, E = 0	I_{ro}		1	3	nA
Diode capacitance	V_R = 0 V, f = 1 MHz, E = 0	C_D		4		pF
	V_R = 5 V, f = 1 MHz, E = 0	C_D		1.3		pF
Open circuit voltage	E_e = 1 mW/cm², λ = 950 nm	V_o		350		mV
Temperature coefficient of V_o	E_e = 1 mW/cm², λ = 950 nm	TK_{Vo}		- 2.6		mV/K
Short circuit current	E_e = 1 mW/cm², λ = 950 nm	I_k		3		µA
Temperature coefficient of I_k	E_e = 1 mW/cm², λ = 950 nm	TK_{Ik}		0.1		%/K
Reverse light current	E_e = 1 mW/cm², λ = 950 nm, V_R = 5 V	I_{ra}	2.4	3	3.6	µA
Angle of half sensitivity		φ		± 60		deg
Wavelength of peak sensitivity		λ_p		900		nm
Range of spectral bandwidth		$\lambda_{0.1}$		430 to 1100		nm
Rise time	V_R = 10 V, R_L = 1 kΩ, λ = 820 nm	t_r		100		ns
Fall time	V_R = 10 V, R_L = 1 kΩ, λ = 820 nm	t_f		100		ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

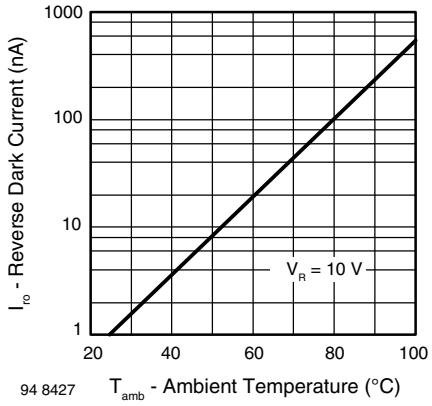


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

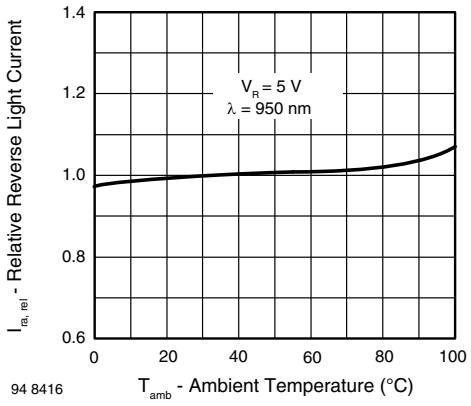


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature

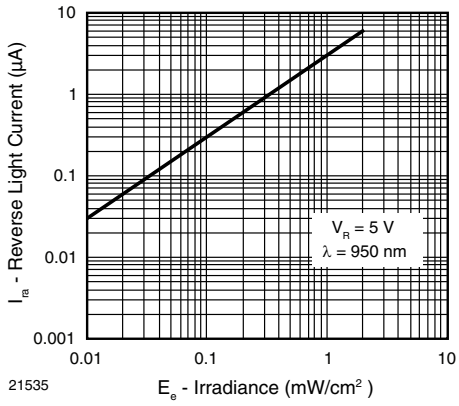


Fig. 3 - Reverse Light Current vs. Irradiance

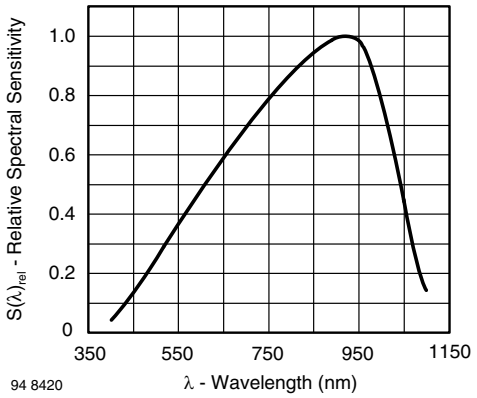


Fig. 6 - Relative Spectral Sensitivity vs. Wavelength

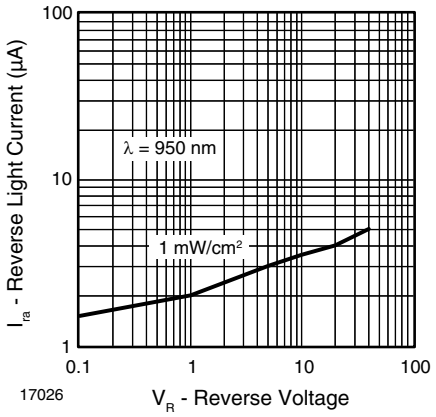


Fig. 4 - Reverse Light Current vs. Reverse Voltage

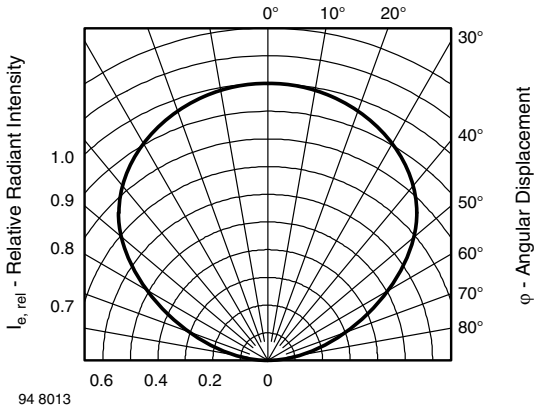


Fig. 7 - Relative Radiant Intensity vs. Angular Displacement

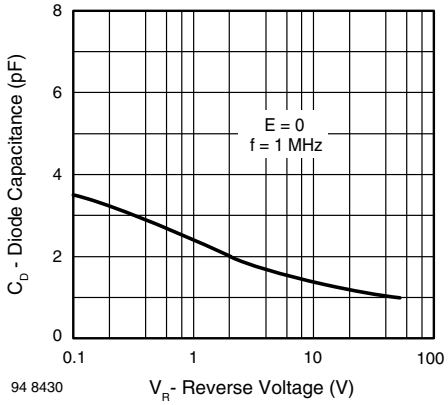


Fig. 5 - Diode Capacitance vs. Reverse Voltage

REFLOW SOLDER PROFILE

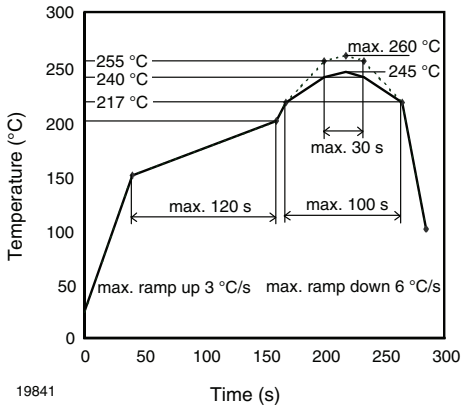


Fig. 8 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

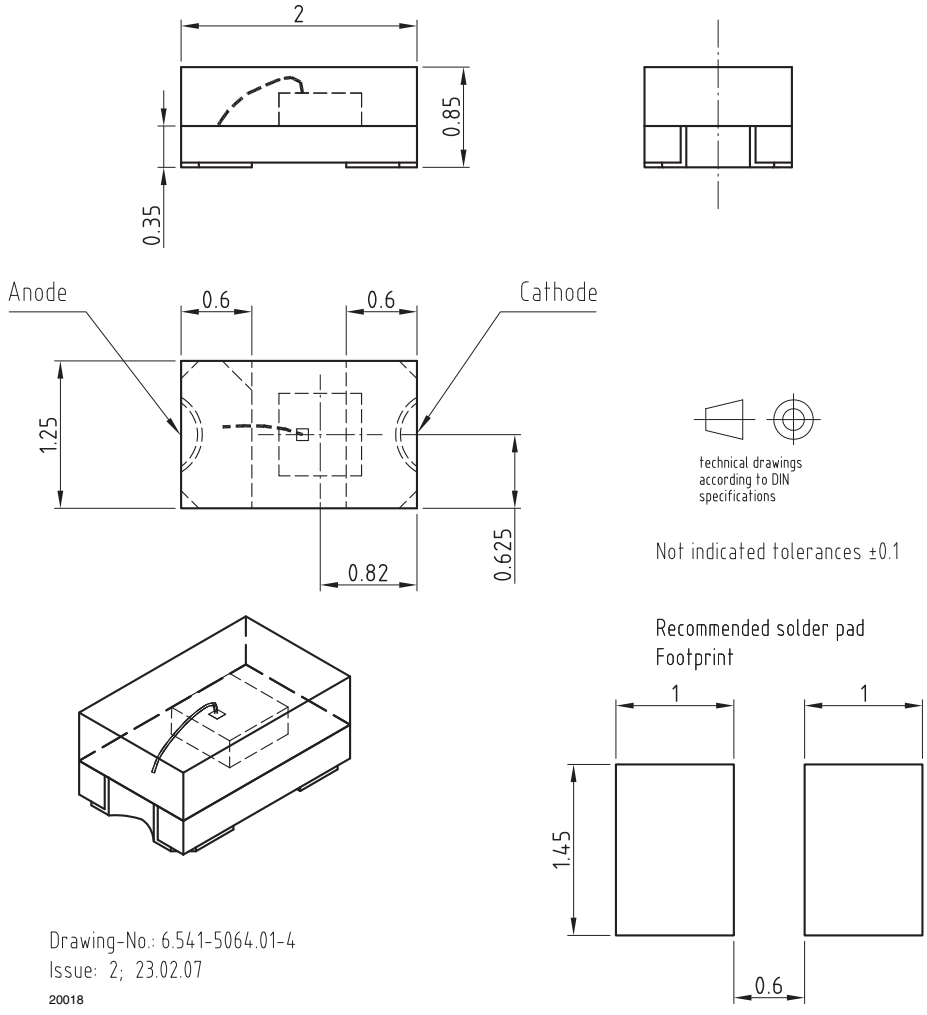
FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:
Floor life: 168 h
Conditions: T_{amb} < 30 °C, RH < 60 %
Moisture sensitivity level 3, acc. to J-STD-020.

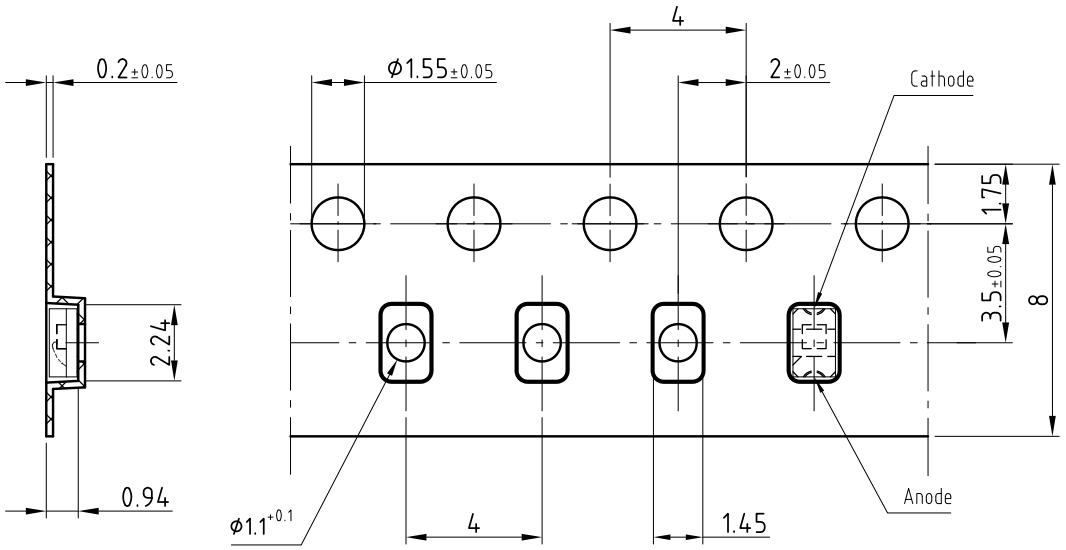
DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

PACKAGE DIMENSIONS in millimeters



BLISTER TAPE DIMENSIONS in millimeters

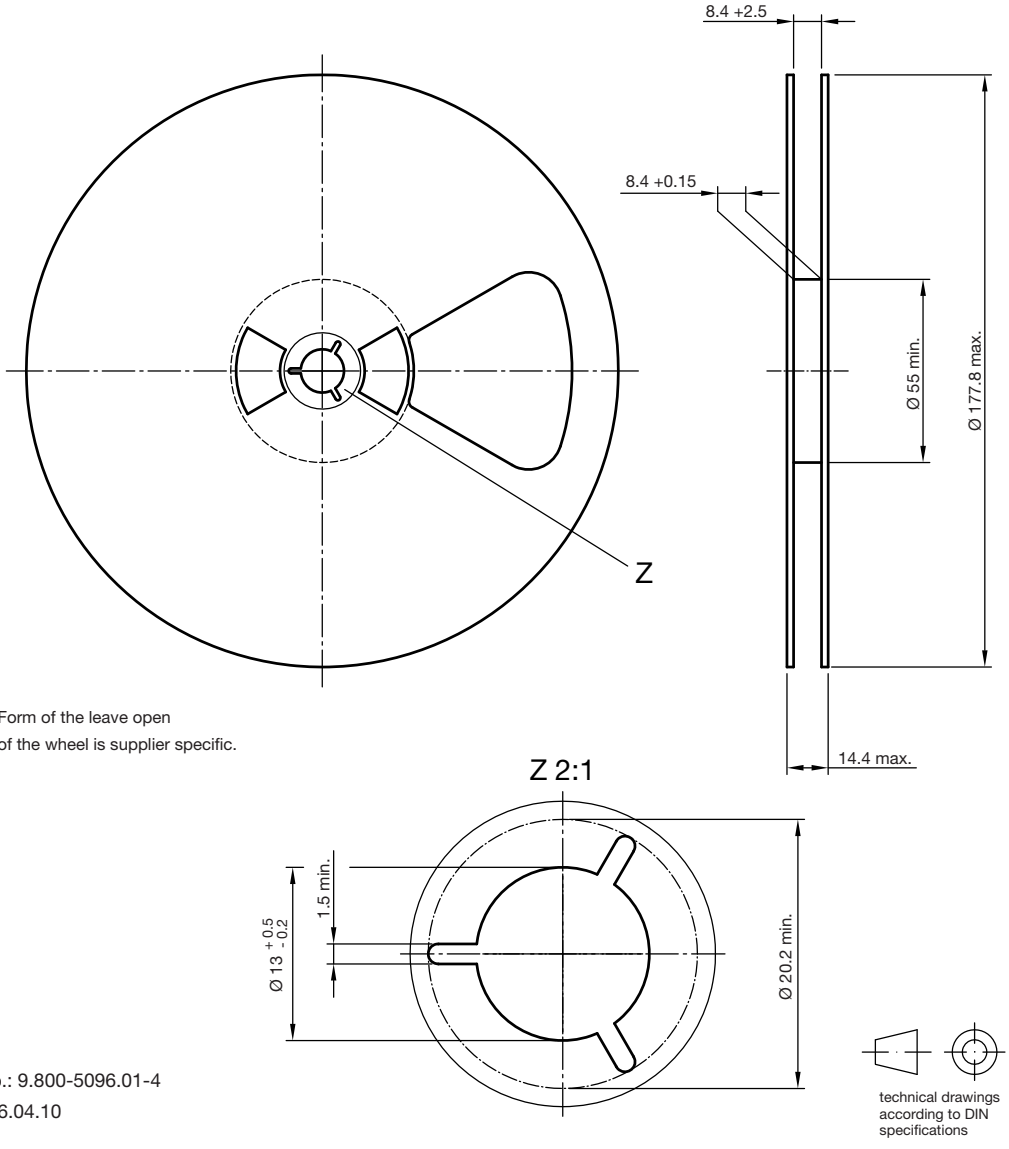


technical drawings
according to DIN
specifications

Drawing-No.: 9.700-5311.01-4
Issue: 1; 23.02.07
21501

Not indicated tolerances ±0.1

REEL DIMENSIONS in millimeters



Form of the leave open
of the wheel is supplier specific.

Drawing-No.: 9.800-5096.01-4
Issue: 2; 26.04.10
20875

technical drawings
according to DIN
specifications

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